

# Yulong Li

## List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Microstructure evolution and shear fracture behavior of aged Sn3Ag0.5Cu/Cu solder joints. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 673, 167-177.	2.6	124
2	Influences of Mono-Ni(P) and Dual-Cu/Ni(P) Plating on the Interfacial Microstructure Evolution of Solder Joints. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2019, 50, 480-492.	1.1	90
3	Shear strength and fracture behavior of reflowed Sn3.0Ag0.5Cu/Cu solder joints under various strain rates. <i>Journal of Alloys and Compounds</i> , 2017, 690, 720-729.	2.8	86
4	Metal coating of fiber Bragg grating and the temperature sensing character after metallization. <i>Optical Fiber Technology</i> , 2009, 15, 391-397.	1.4	81
5	Interfacial reaction and IMC growth between Bi-containing Sn0.7Cu solders and Cu substrate during soldering and aging. <i>Journal of Alloys and Compounds</i> , 2014, 582, 341-347.	2.8	77
6	Developments of high strength Bi-containing Sn0.7Cu lead-free solder alloys prepared by directional solidification. <i>Journal of Alloys and Compounds</i> , 2015, 625, 241-250.	2.8	69
7	Blind MuseumTourer: A System for Self-Guided Tours in Museums and Blind Indoor Navigation. <i>Technologies</i> , 2018, 6, 4.	3.0	59
8	Heat input, intermetallic compounds and mechanical properties of Al/steel cold metal transfer joints. <i>Journal of Materials Processing Technology</i> , 2019, 272, 40-46.	3.1	58
9	Dissimilar Laser Welding/Brazing of 5754 Aluminum Alloy to DP 980 Steel: Mechanical Properties and Interfacial Microstructure. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2015, 46, 5149-5157.	1.1	57
10	Microstructure and shear strength of Sn37Pb/Cu solder joints subjected to isothermal aging. <i>Microelectronics Reliability</i> , 2014, 54, 1575-1582.	0.9	53
11	Ultrasonic embedding of nickel-coated fiber Bragg grating in aluminum and associated sensing characteristics. <i>Optical Fiber Technology</i> , 2012, 18, 7-13.	1.4	52
12	Mechanical properties of directionally solidified Nb-Mo-Si-based alloys with aligned Nbss/Nb5Si3 lamellar structure. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 528, 5772-5777.	2.6	47
13	Interface structure and mechanical properties of the TiAl/42CrMo steel joint vacuum brazed with Ag-Cu/Ti/Ag-Cu filler metal. <i>Scripta Materialia</i> , 2006, 55, 171-174.	2.6	45
14	Ultrahigh-temperature Nbss/Nb5Si3 fully-lamellar microstructure developed by directional solidification in OFZ furnace. <i>Intermetallics</i> , 2011, 19, 460-469.	1.8	45
15	Influence of alloy elements on microstructure and mechanical properties of Al/steel dissimilar joint by laser welding/brazing. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2018, 62, 427-433.	1.3	42
16	Capillary Rise of Liquids over a Microstructured Solid Surface. <i>Langmuir</i> , 2011, 27, 14260-14266.	1.6	36
17	Laser welding/brazing of 5182 aluminium alloy to ZEK100 magnesium alloy using a nickel interlayer. <i>Science and Technology of Welding and Joining</i> , 2018, 23, 543-550.	1.5	35
18	Interfacial reaction and growth behavior of IMCs layer between Sn-58Bi solders and a Cu substrate. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 2027-2034.	1.1	34

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19	Wetting kinetics and spreading phenomena of the precursor film and bulk liquid in the AgCuTi/TC4 system. <i>Journal of Alloys and Compounds</i> , 2019, 802, 345-354.	2.8	34
20	Reactive wetting of AgCuTi filler metal on the TiAl-based alloy substrate. <i>Applied Surface Science</i> , 2012, 259, 343-348.	3.1	33
21	Microstructure and mechanical properties of Ti-6Al-4V prepared by nickel preplating and electron beam surface remelting. <i>Journal of Materials Processing Technology</i> , 2019, 271, 420-428.	3.1	33
22	Microstructure and wear resistance of a Ni-WC composite coating on titanium grade 2 obtained by electroplating and electron beam remelting. <i>Materials Characterization</i> , 2020, 170, 110674.	1.9	33
23	Temperature and strain sensing properties of the zinc coated FBG. <i>Optik</i> , 2016, 127, 6463-6469.	1.4	28
24	Wetting and spreading behaviors of Al-Si alloy on surface textured stainless steel by ultrafast laser. <i>Applied Surface Science</i> , 2020, 520, 146316.	3.1	28
25	The growth behavior of interfacial intermetallic compound between Sn <sup>3.5</sup> Ag <sup>0.5</sup> Cu solder and Cu substrate under different thermal-aged conditions. <i>Journal of Materials Science: Materials in Electronics</i> , 2017, 28, 18515-18528.	1.1	27
26	Microstructure and mechanical properties of laser fusion welded Al/steel joints using a Zn-based filler wire. <i>Optics and Laser Technology</i> , 2020, 122, 105882.	2.2	26
27	Effect of Ni addition to the Cu substrate on the interfacial reaction and IMC growth with Sn <sup>3.0</sup> Ag <sup>0.5</sup> Cu solder. <i>Applied Physics A: Materials Science and Processing</i> , 2018, 124, 1.	1.1	25
28	Shear strengths and fracture behaviors of Cu/Sn <sup>37</sup> Pb/Cu soldered joints subjected to different displacement rates. <i>Journal of Alloys and Compounds</i> , 2014, 600, 13-20.	2.8	23
29	Effects of post-reflow cooling rate and thermal aging on growth behavior of interfacial intermetallic compound between SAC305 solder and Cu substrate. <i>Applied Physics A: Materials Science and Processing</i> , 2016, 122, 1.	1.1	23
30	Fabrication, microstructure, and wear performance of WC-Fe composite/metal coating fabricated by resistance seam welding. <i>Materials Characterization</i> , 2017, 134, 182-193.	1.9	23
31	Effect of strain rate on interfacial fracture behaviors of Sn-58Bi/Cu solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 57-64.	1.1	21
32	Interfacial microstructure evolution and shear strength of Sn <sup>0.7</sup> Cu <sup>x</sup> Ni/Cu solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 11314-11324.	1.1	21
33	Tensile properties of Cu/Sn <sup>58</sup> Bi/Cu soldered joints subjected to isothermal aging. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 2416-2425.	1.1	20
34	Shear strength and fracture surface analysis of Sn58Bi/Cu solder joints under a wide range of strain rates. <i>Microelectronics Reliability</i> , 2018, 86, 27-37.	0.9	19
35	Diode Laser Welding/Brazing of Aluminum Alloy to Steel Using a Nickel Coating. <i>Applied Sciences (Switzerland)</i> , 2018, 8, 922.	1.3	19
36	Dissolution of TiAl alloy during high temperature brazing. <i>Journal of Materials Science</i> , 2013, 48, 5247-5252.	1.7	18

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37	Effect of Cu <sub>6</sub> Sn <sub>5</sub> nanoparticle on thermal behavior, mechanical properties and interfacial reaction of Sn <sub>3.0</sub> Ag <sub>0.5</sub> Cu solder alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 15983-15993.	1.1	18
38	Light intensity modulation temperature sensor based on U-shaped bent single-mode fiber. <i>Optik</i> , 2017, 130, 813-817.	1.4	17
39	Temperature sensing characteristics of metal coated FBG during dynamic cooling process. <i>Optical Fiber Technology</i> , 2018, 45, 368-375.	1.4	17
40	Microstructure and mechanical properties of the Ni-B-Ti composite coating on TA2 prepared by pre-plating and laser remelting. <i>Surface and Coatings Technology</i> , 2021, 405, 126567.	2.2	17
41	Intensity-modulated refractive index sensor based on the side modes of fiber Bragg grating. <i>Optics Communications</i> , 2022, 505, 127319.	1.0	16
42	Simultaneous measurement of the temperature and force using a steel cantilever soldered with a partially nickel coated in-fibre Bragg grating. <i>Optics Communications</i> , 2012, 285, 4275-4279.	1.0	15
43	Effect of Bi Segregation on the Asymmetrical Growth of Cu-Sn Intermetallic Compounds in Cu/Sn-58Bi/Cu Sandwich Solder Joints During Isothermal Aging. <i>Journal of Electronic Materials</i> , 2013, 42, 3567-3572.	1.0	15
44	Interfacial Reaction and IMC Growth of an Ultrasonically Soldered Cu/SAC305/Cu Structure during Isothermal Aging. <i>Materials</i> , 2018, 11, 84.	1.3	15
45	Cost-affordable, high-performance Ti <sub>40</sub> TiB composite for selective laser melting additive manufacturing. <i>Journal of Materials Research</i> , 2020, 35, 1922-1935.	1.2	15
46	Interfacial reaction and IMCs growth behavior of Sn <sub>3</sub> Ag <sub>0.5</sub> Cu/Ni solder bump during aging at various temperatures. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 4245-4252.	1.1	14
47	Comparative study of wear performance of ceramic/iron composite coatings under two different wear modes. <i>Surface and Coatings Technology</i> , 2017, 309, 136-148.	2.2	14
48	Interfacial reaction and microstructure between the Sn <sub>3</sub> Ag <sub>0.5</sub> Cu solder and Cu <sub>60</sub> Co dual-phase substrate. <i>Applied Physics A: Materials Science and Processing</i> , 2018, 124, 1.	1.1	14
49	Effects of thermal aging on growth behavior of interfacial intermetallic compound of dip soldered Sn/Cu joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 8863-8875.	1.1	13
50	Interfacial IMC growth of SAC305/Cu joint with a novel dual-layer of Ni(P)/Cu plating during solid-state aging. <i>Microelectronic Engineering</i> , 2018, 199, 69-79.	1.1	13
51	Interfacial reaction, wettability, and shear strength of ultrasonic-assisted lead-free solder joints prepared using Cu <sub>60</sub> GNSs-doped flux. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 24507-24523.	1.1	13
52	Growth behavior of IMCs layer of the Sn <sub>35</sub> Ag <sub>1</sub> on Cu, Ni <sub>3</sub> P/Cu and Ni <sub>3</sub> Co <sub>3</sub> P/Cu substrates during aging. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 1519-1530.	1.1	12
53	Preparation of high performance Fe-based amorphous coating by resistance seam welding. <i>Surface and Coatings Technology</i> , 2021, 408, 126813.	2.2	12
54	Vacuum wetting of Ag/TA2 to develop a novel micron porous Ti with significant biocompatibility and antibacterial activity. <i>Journal of Materials Science and Technology</i> , 2022, 116, 180-191.	5.6	12

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55	A study on the interfacial reaction of Sn58Bi/Cu soldered joints under various cooling and aging conditions. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 5140-5151.	1.1	11
56	Wetting kinetics and spreading phenomena of Sn-35Bi-1Ag solder on different substrates. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 13914-13924.	1.1	11
57	Laser 3D Printing of Fe-Based Bulk Metallic Glass: Microstructure Evolution and Crack Propagation. <i>Journal of Materials Engineering and Performance</i> , 2019, 28, 3478-3486.	1.2	11
58	An Electroplating Method for Surface Mounting Optical Fiber Sensors on the Metal Substrate. <i>IEEE Photonics Technology Letters</i> , 2016, 28, 1811-1814.	1.3	10
59	Effects of metal coating on the fiber Bragg grating temperature sensing characteristics. <i>Journal of Modern Optics</i> , 2016, 63, 762-770.	0.6	10
60	Effect of temperature and substrate surface roughness on wetting behavior and interfacial structure between Sn-35Bi-1Ag solder and Cu substrate. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 4224-4236.	1.1	10
61	Swirl-like Cu-Sn phase formation and the effects on the ultrasonic spot welded joint of Sn-coated Cu plates. <i>Journal of Materials Processing Technology</i> , 2021, 288, 116911.	3.1	10
62	Capillary encapsulating of fiber Bragg grating and the associated sensing model. <i>Optics Communications</i> , 2014, 333, 92-98.	1.0	9
63	Effect of alloying Cu substrate on microstructure and coarsening behavior of Cu <sub>6</sub> Sn <sub>5</sub> grains of soldered joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 2782-2794.	1.1	9
64	Effect of Ni Addition to Sn <sub>0.7</sub> Cu Solder Alloy on Thermal Behavior, Microstructure, and Mechanical Properties. <i>Journal of Materials Engineering and Performance</i> , 2018, 27, 6564-6576.	1.2	9
65	Microstructural evolution of unidirectionally solidified NbSS-Nb <sub>5</sub> Si <sub>3</sub> eutectic alloy. <i>Rare Metals</i> , 2011, 30, 335-339.	3.6	7
66	Preferential spreading of molten metal over an anisotropically microstructured surface. <i>Europhysics Letters</i> , 2012, 97, 46003.	0.7	7
67	Effects of In addition on the wettability, interfacial characterization and properties of ternary Sn-Cu-Ni solders. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 18840-18851.	1.1	7
68	Effect of electroplating parameters on electroplated Cu film and microvoid formation of solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 18404-18416.	1.1	7
69	Interfacial reaction between liquid-state Sn-xBi solder and Co substrate. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 9155-9165.	1.1	6
70	Mechanical properties of CoSn <sub>2</sub> and $\hat{I}$ -CoSn <sub>3</sub> intermetallic compounds: first-principles calculations and nano-indentation measurements. <i>Applied Physics A: Materials Science and Processing</i> , 2019, 125, 1.	1.1	6
71	Theoretical and experimental study of macrobending losses in coated single-mode fibers. <i>Optical Engineering</i> , 2017, 56, 066102.	0.5	5
72	Influence of Zn additions on the interfacial reaction and microstructure of Sn <sub>37</sub> Pb/Cu solder joints. <i>Applied Physics A: Materials Science and Processing</i> , 2017, 123, 1.	1.1	5

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73	Effects of germanium on the microstructural, mechanical and thermal properties of Sn-0.7Cu solder alloy. <i>Materials Research Express</i> , 2019, 6, 016556.	0.8	5
74	Effects of Zn contents on microstructure, thermodynamic characteristic and mechanical properties of Sn-Bi-based lead-free solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 1741-1751.	1.1	5
75	Enhancing the properties of the SAC305-soldered joint: heat treatment of the nickel-plated copper substrate before reflow soldering. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 3535-3545.	1.1	5
76	Wetting kinetics of the AgCuTi filler metal on pure molybdenum substrate. <i>Surface and Interface Analysis</i> , 2015, 47, 838-843.	0.8	4
77	Experimental Study and Fractal Analysis on the Anisotropic Performance of Explosively Welded Interfaces of 304 Stainless Steel/245 Carbon Steel. <i>Journal of Materials Engineering and Performance</i> , 2018, 27, 2556-2565.	1.2	4
78	A Fiber Bragg Grating Sensing Structure for the Design, Simulation and Stress Strain Monitoring of Human Puncture Surgery. <i>Sensors</i> , 2019, 19, 3066.	2.1	4
79	Microstructure evolution and wettability of Ag Cu Zn alloy on TiC Ni cermet. <i>Vacuum</i> , 2019, 159, 500-506.	1.6	4
80	Influence of Bi Addition on Pure Sn Solder Joints: Interfacial Reaction, Growth Behavior and Thermal Behavior. <i>Journal Wuhan University of Technology, Materials Science Edition</i> , 2019, 34, 668-675.	0.4	4
81	Significant Inhibition of IMCs Growth between an Electroless Ni-W-P Metallization and SAC305 Solder During Soldering and Aging. <i>Journal Wuhan University of Technology, Materials Science Edition</i> , 2019, 34, 165-175.	0.4	4
82	An In-Situ Electroplating Fabricated Fabry-Perot Interferometric Sensor and Its Temperature Sensing Characteristics. <i>Coatings</i> , 2020, 10, 1174.	1.2	4
83	Mechanical response of reaction phases of the TiAl/steel brazed joint under a tensile load. <i>Journal of Materials Science</i> , 2014, 49, 1114-1120.	1.7	3
84	Metal coatings on long-period fiber gratings and the implementation of an associated sensing model. <i>Applied Physics A: Materials Science and Processing</i> , 2017, 123, 1.	1.1	3
85	Wetting Kinetics and Microstructure Analysis of BNi2 Filler Metal over Selective Laser Melted Ti-6Al-4V Substrate. <i>Materials</i> , 2020, 13, 4666.	1.3	3
86	Wetting and Spreading of AgCuTi on Selective Laser-Melted Ti-6Al-4V. <i>Materials</i> , 2021, 14, 4804.	1.3	3
87	Mechanical response of the TiAl/steel brazed joint under impact load. <i>Journal of Materials Science</i> , 2009, 44, 3077-3081.	1.7	2
88	Simulation and experiment of packaging of the fibre Bragg grating sensors using brazing/soldering methods. <i>Journal of Modern Optics</i> , 2016, 63, 1414-1419.	0.6	2
89	Real-time in situ monitoring of internal stress of the electroplating processes using FBG sensors. <i>Applied Physics A: Materials Science and Processing</i> , 2019, 125, 1.	1.1	2
90	Wetting kinetics and interfacial structure of AgCu alloy spreading on TB8 substrates. <i>Materials Research Express</i> , 2019, 6, 0865e8.	0.8	2

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91	Theoretical Modeling and Experimental Studies of Ultra-Thin Chip Transfer in Laser-Induced Forward Transfer. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 570-577.	1.4	2
92	The complete sequence of mitochondrial COII gene of Fenneropenaeus chinensis and its applicability as a marker for phylogenetic analysis. Journal of Ocean University of China, 2007, 6, 187-192.	0.6	1
93	A study of the microstructure, thermal properties and wetting kinetics of Sn-3Ag-xZn lead-free solders. Applied Physics A: Materials Science and Processing, 2016, 122, 1.	1.1	1
94	Interfacial IMC Growth and Nanomechanical Characterizations of Solder in Sn-16Sb/Cu Joints during Solid-state Aging. Journal Wuhan University of Technology, Materials Science Edition, 2019, 34, 1210-1219.	0.4	1
95	Research on Interfacial Reaction and Growth Behavior of Intermetallic Compound of Dip-Soldered Sn/Ni System. Transactions of the Indian Institute of Metals, 2019, 72, 651-661.	0.7	1
96	Thermal Process Analysis in Welding Prototyping of Metal Structures. Lecture Notes in Electrical Engineering, 2011, , 383-390.	0.3	1
97	Study on the performance of Cu foam with different porosity on SAC305 solder joints under ultrasonic-assisted soldering. Journal of Materials Science: Materials in Electronics, 2021, 32, 28108.	1.1	1
98	Effect of Bi on microstructure and mechanical properties of Sn-10Sb-1.5Cu (SSC1015) solder alloys. Materials Research Express, 2019, 6, 026565.	0.8	0
99	A novel method for fabricating micron-scale porous structure on the surface of commercially-pure Ti. Materials Letters, 2021, 294, 129802.	1.3	0